

**TPM Annual Scholarship Program**

The Timber Products Manufacturers (TPM) Association offers scholarships to Applicants who are employees or dependents of employees of TPM Association member companies and meet the necessary requirements. TPM will consider all students entering or attending college, university or trade school, regardless of what year of program they are attending. The TPM Board of Directors may consider multiple year scholarships for individuals pursuing a wood products related field or industry.

The TPM Board of Directors will review the applications at the Spring Board meeting and present the winners at the Annual Meeting in June. The winners of the scholarship will be invited to the TPM summer meeting to receive their award at the TPM evening social and dinner.

Applications for the scholarship are to be submitted to the TPM office located at 951 East Third Avenue, Spokane, WA, 99202, by January 31, 2026.

TPM will not discriminate in the decision-making process of choosing the appropriate individual for the scholarship. All applicants must have met the required criteria in order to be eligible to win the scholarship. The scholarship by law, once given, cannot be rescinded if the family member leaves the TPM member company.

All scholarships will be paid directly to the accepted school of choice. Due to IRS rules, the scholarship cannot and will not be paid directly to the student.

Criteria for TPM scholarship:

1. Completed Application
2. Student Essay
3. High School, college or trade school transcripts/minimum 3.0 GPA
4. Activities participated in during high school or higher education
5. Acceptance letter to school of choice
6. The person must work, or be a dependent of an employee who works, for a TPM Association member company.
7. The scholarship is a one-time award. Multiple year awards may be considered for awardees pursuing a career in a wood products related field or industry.
8. A minimum of two, $500 scholarships will be awarded each year.
9. The TPM Board of Directors has discretion to award additional scholarships.
10. The applicant must be a citizen of the United States

**NOTE: Incomplete scholarship packet submissions will be rejected.**



**TPM Scholarship Application**

The Timber Products Manufacturers Association is pleased to offer an academic collegiate/trade school scholarship for TPM members and their dependents.

**Eligibility**

Students who meet the following criteria are eligible for the scholarship. The candidate:

1. Is an employee, or a dependent of an employee, of a member company of the TPM Association.
2. Is a citizen of the United States of America
3. Has a minimum G.P.A. of 3.0 and is either enrolled full-time, has graduated from high school, or has obtained a U.S. GED at the time of application. Must provide high school, college or trade school transcripts.

**Application Process**

Applications must be received by January 31, 2026, in order to be considered. The following materials are to be submitted:

1. Completed Application Form
2. A **typed** one-page essay on a separate sheet of paper addressing one of the following topics:
   1. Why do you want to major in the program you are choosing?
   2. What impact does your major have on society?
   3. What are your career aspirations and why?
   4. Explain why the timber industry is important to you.
3. A letter of recommendation from a coach, teacher, or an adult that is not an immediate family member.
4. Letter of acceptance to the college of choice.
5. An official high school, college, university or trade school transcript or letter signifying that you have met the requirements of the State GED.

**NOTE: Incomplete scholarship packet submissions will be rejected.**

**Selection Process**

Recipients will be selected by the TPM Board of Directors based on the application materials. All applicants will be notified by April 1st. Payment will be made to the recipient’s school of choice upon notification and in accordance with the school’s scholarship guidelines.

**Purpose of Scholarship**

To provide financial assistance to students of TPM member companies in the wood products industry.

**Award**

TPM will award a minimum of two, $500.00 scholarships to different individuals each year, paid to the recipient’s educational institution.

**Questions**

If you have questions or need further information, please contact Adam Molenda at amolenda@tpmrs.com.



**Timber Products Manufacturers Association Scholarship Application**

Please complete this form. Information must be typed or printed directly on this form.

Member Company Name: \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

Applicant Name: \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ Age: \_\_\_\_\_\_\_\_\_\_\_\_

Home Address:

\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

Home Phone:

Email Address:

Parent or Guardian’s name:

Overall GPA:

College, University or Trade School name: \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

College, University or Trade School Address, City, State, ZIP: \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

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College, University or Trade School Admissions office phone number: \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

Anticipated Major:

Expected College Graduation Date:

Honors:

Activities/Sports:

Community Involvement:

Other Activities or Circumstances that should be considered:

**All** application materials must be received by **January 31st** in order to be considered. **The scholarship application and all its requirements must be completed in full or it will be rejected**.

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Send completed application materials to:

TPM

Attention: Adam Molenda

951 East Third Avenue

Spokane, WA 99202

amolenda@tpmrs.com

In accordance with the Privacy Act of 1974, I agree that my signature on this form will authorize the scholarship chairperson(s) to release copies of my transcripts, scholarship application, and other auxiliary data to the Scholarship Committee as needed. I certify that the information contained in this application is accurate to the best of my knowledge and belief. I certify that the composition submitted was written by me. If awarded a scholarship, I agree to abide by and fulfill all requirements listed in the guidelines.

Applicant Date

Parent/Legal Guardian Date

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